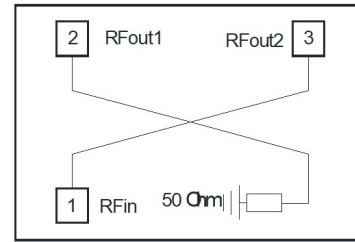


Performance

- Frequency: 8-12GHz
- Insertion loss: 1.0dB
- Chip size: 0.9*2.2*0.1mm

Function Diagram

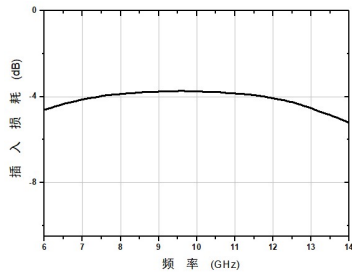


Electrical Specifications (Ta=+25°C, 50Ω system)

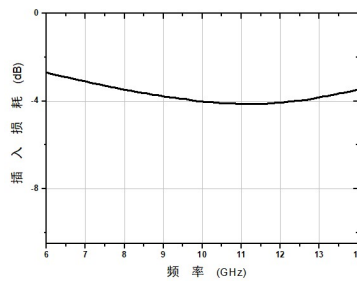
Parameter	Min	Typical	Max	Unit
Frequency Range	8-12			GHz
Insertion Loss	-	1.0	-	dB
Input Return loss	-	20	-	dB
Output Return loss	-	15	-	dB
Isolation	-	20	-	dB

Test Curves

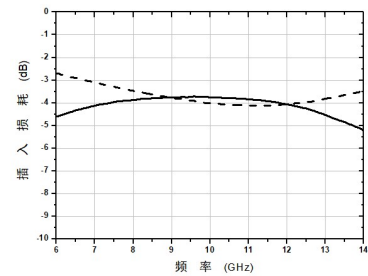
Insertion loss vs. Freq



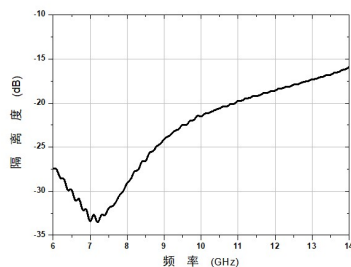
Insertion loss vs. Freq



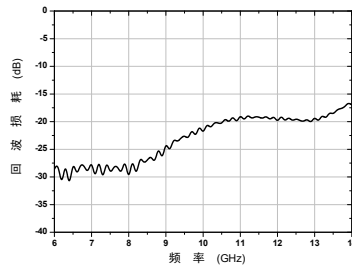
Insertion loss vs. Freq



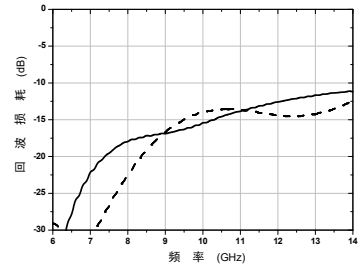
Isolation vs. Freq



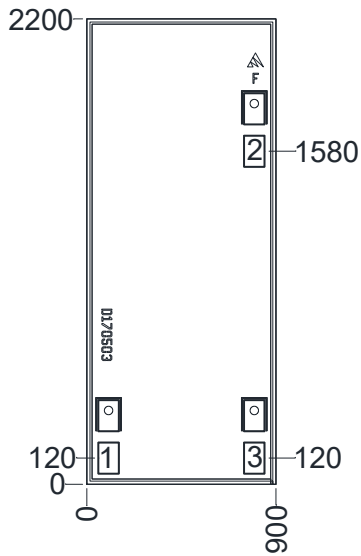
Input Return loss vs. Freq



Output Return loss vs. Freq



Outline Size



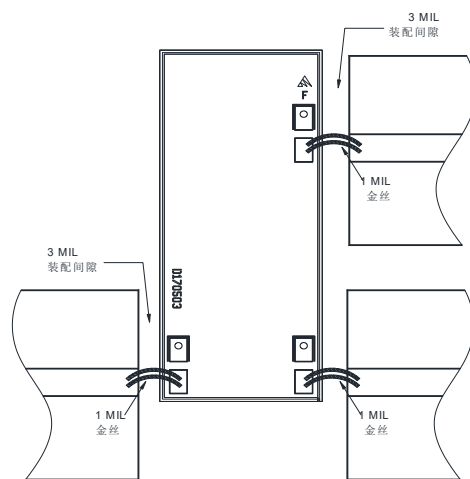
Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, size: $150 \times 100(\mu\text{m})$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50\mu\text{m}$

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input, 50ohm
2,3	RFout 1, RFout2	RF output port, 50ohm
-	GND	Bottom must be GND

Application



Absolute Max Ratings

Max Input Power	+46dBm
Static Class	Class 1A
Storage Temperature	-65 ~ +150°C
Operating Temperature	-55 ~ +125°C

Note: For high power application, assemble with Eutectic sintering.



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS